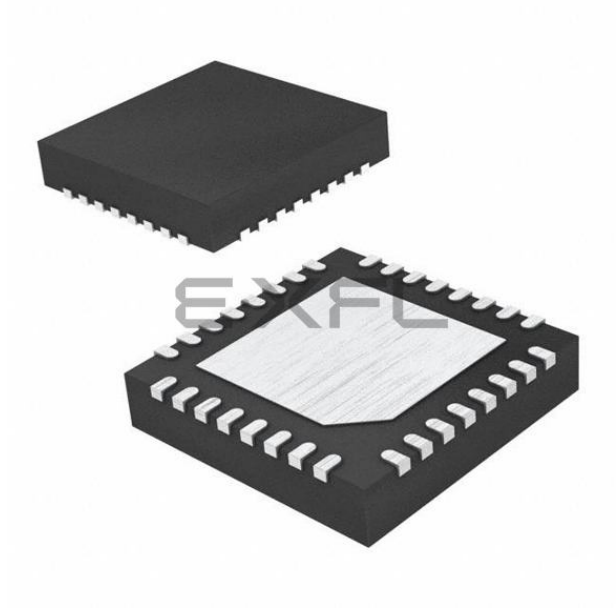
Microchip Technology - PIC24FJ128GA202-E/MM Datasheet



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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, DMA, LVD, POR, PWM, WDT
Number of I/O	21
Program Memory Size	128KB (43K x 24)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 3.6V
Data Converters	A/D 10x10b/12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN-S (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24fj128ga202-e-mm

REGISTER 5-3: DMAINTn: DMA CHANNEL n INTERRUPT REGISTER

R-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
DBUFWF(1)	—	CHSEL5	CHSEL4	CHSEL3	CHSEL2	CHSEL1	CHSEL0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	U-0	U-0	R/W-0
HIGHIF(1,2)	LOWIF(1,2)	DONEIF(1)	HALFIF(1)	OVRUNIF(1)	—	—	HALFEN
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **DBUFWF:** DMA Buffered Data Write Flag bit(1)
- 1 = The content of the DMA buffer has not been written to the location specified in DMADSTn or DMASRCn in Null Write mode
- 0 = The content of the DMA buffer has been written to the location specified in DMADSTn or DMASRCn in Null Write mode

bit 14 **Unimplemented:** Read as '0'

bit 13-8 **CHSEL<5:0>:** DMA Channel Trigger Selection bits

See Table 5-1 for a complete list.

bit 7 **HIGHIF:** DMA High Address Limit Interrupt Flag bit(1,2)
- 1 = The DMA channel has attempted to access an address higher than DMAH or the upper limit of the data RAM space
- 0 = The DMA channel has not invoked the high address limit interrupt

bit 6 **LOWIF:** DMA Low Address Limit Interrupt Flag bit(1,2)
- 1 = The DMA channel has attempted to access the DMA SFR address lower than DMAL, but above the SFR range (07FFh)
- 0 = The DMA channel has not invoked the low address limit interrupt

bit 5 **DONEIF:** DMA Complete Operation Interrupt Flag bit(1)

If CHEN = 1:
- 1 = The previous DMA session has ended with completion
- 0 = The current DMA session has not yet completed

If CHEN = 0:
- 1 = The previous DMA session has ended with completion
- 0 = The previous DMA session has ended without completion

bit 4 **HALFIF:** DMA 50% Watermark Level Interrupt Flag bit(1)
- 1 = DMACNTn has reached the halfway point to 0000h
- 0 = DMACNTn has not reached the halfway point

bit 3 **OVRUNIF:** DMA Channel Overrun Flag bit(1)
- 1 = The DMA channel is triggered while it is still completing the operation based on the previous trigger
- 0 = The overrun condition has not occurred

bit 2-1 **Unimplemented:** Read as '0'

bit 0 **HALFEN:** DMA Halfway Completion Watermark bit
- 1 = Interrupts are invoked when DMACNTn has reached its halfway point and at completion
- 0 = An interrupt is invoked only at the completion of the transfer

Note 1: Setting these flags in software does not generate an interrupt.

2: Testing for address limit violations (DMASRCn or DMADSTn is either greater than DMAH or less than DMAL) is NOT done before the actual access.

7.0 RESETS

Note: This data sheet summarizes the features of this group of PIC24F devices. It is not intended to be a comprehensive reference source. For more information, refer to the *"dsPIC33/PIC24 Family Reference Manual"*, **"Reset"** (DS39712). The information in this data sheet supersedes the information in the FRM.

The Reset module combines all Reset sources and controls the device Master Reset Signal, $\overline{SYSRST}$. The following is a list of device Reset sources:

- POR: Power-on Reset
- $\overline{MCLR}$: Master Clear Pin Reset
- SWR: RESET Instruction
- WDT: Watchdog Timer Reset
- BOR: Brown-out Reset
- CM: Configuration Mismatch Reset
- TRAPR: Trap Conflict Reset
- IOPUWR: Illegal Opcode Reset
- UWR: Uninitialized W Register Reset

A simplified block diagram of the Reset module is shown in Figure 7-1.

Any active source of Reset will make the $\overline{SYSRST}$ signal active. Many registers associated with the CPU and peripherals are forced to a known Reset state. Most registers are unaffected by a Reset; their status is unknown on POR and unchanged by all other Resets.

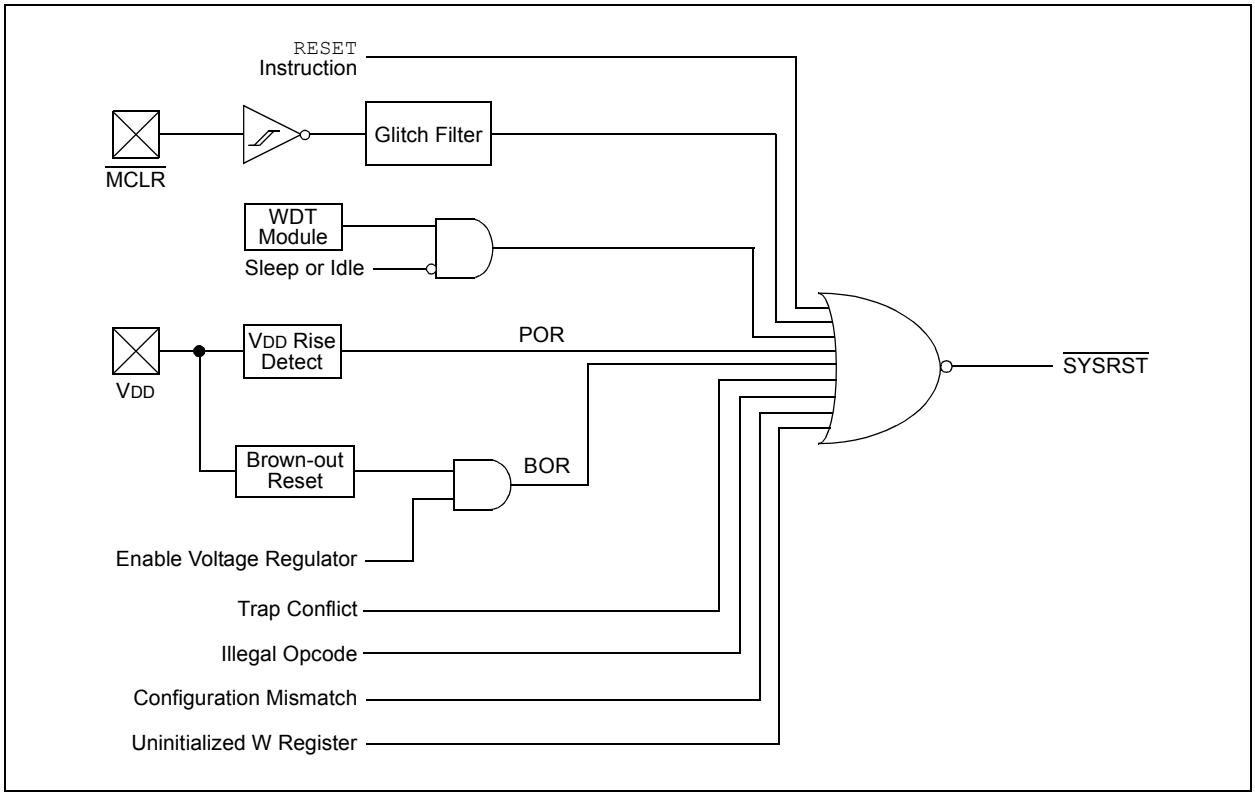
Note: Refer to the specific peripheral or CPU section of this manual for register Reset states.

All types of device Resets will set a corresponding status bit in the RCON register to indicate the type of Reset (see Register 7-1). In addition, Reset events occurring while an extreme power-saving feature is in use (such as VBAT) will set one or more status bits in the RCON2 register (Register 7-2). A POR will clear all bits, except for the BOR and POR (RCON<1:0>) bits, which are set. The user may set or clear any bit at any time during code execution. The RCON bits only serve as status bits. Setting a particular Reset status bit in software will not cause a device Reset to occur.

The RCON register also has other bits associated with the Watchdog Timer and device power-saving states. The function of these bits is discussed in other sections of this data sheet.

Note: The status bits in the RCON registers should be cleared after they are read so that the next RCON register values after a device Reset will be meaningful.

FIGURE 7-1: RESET SYSTEM BLOCK DIAGRAM



REGISTER 7-1: RCON: RESET CONTROL REGISTER (CONTINUED)

bit 5 **SWDTEN:** Software Enable/Disable of WDT bit(4)
1 = WDT is enabled
0 = WDT is disabled

bit 4 **WDTO:** Watchdog Timer Time-out Flag bit(1)
1 = WDT time-out has occurred
0 = WDT time-out has not occurred

bit 3 **SLEEP:** Wake from Sleep Flag bit(1)
1 = Device has been in Sleep mode
0 = Device has not been in Sleep mode

bit 2 **IDLE:** Wake from Idle Flag bit(1)
1 = Device has been in Idle mode
0 = Device has not been in Idle mode

bit 1 **BOR:** Brown-out Reset Flag bit(1)
1 = A Brown-out Reset has occurred (also set after a Power-on Reset)
0 = A Brown-out Reset has not occurred

bit 0 **POR:** Power-on Reset Flag bit(1)
1 = A Power-on Reset has occurred
0 = A Power-on Reset has not occurred

Note 1: All of the Reset status bits may be set or cleared in software. Setting one of these bits in software does not cause a device Reset.

2: If the $\overline{\text{LPCFG}}$ Configuration bit is '1' (unprogrammed), the retention regulator is disabled and the RETEN bit has no effect.

3: Re-enabling the regulator after it enters Standby mode will add a delay, T_{VREG}, when waking up from Sleep. Applications that do not use the voltage regulator should set this bit to prevent this delay from occurring.

4: If the FWDTEN Configuration bit is '1' (unprogrammed), the WDT is always enabled**,** regardless of the SWDTEN bit setting.

9.1 CPU Clocking Scheme

The system clock source can be provided by one of four sources:

- Primary Oscillator (POSC) on the OSCI and OSCO pins
- Secondary Oscillator (SOSC) on the SOSCI and SOSCO pins
- Fast Internal RC (FRC) Oscillator
- Low-Power Internal RC (LPRC) Oscillator

The internal FRC provides an 8 MHz clock source. It can optionally be reduced by the programmable clock divider to provide a range of system clock frequencies.

The selected clock source generates the processor and peripheral clock sources. The processor clock source is divided by two to produce the internal instruction cycle clock, FCY. In this document, the instruction cycle clock is also denoted by FOSC/2. The internal instruction cycle clock, FOSC/2, can be provided on the OSCO I/O pin for some operating modes of the Primary Oscillator.

9.2 Initial Configuration on POR

The oscillator source (and operating mode) that is used at a device Power-on Reset event is selected using Configuration bit settings. The Oscillator Configuration bit settings are located in the Configuration registers in program memory (for more information, refer to **Section 29.1 "Configuration Bits"**). The Primary Oscillator Configuration bits, POSCMD<1:0> (Configuration Word 2<1:0>), and the Initial Oscillator Select Configuration bits, FNOSC<2:0> (Configuration Word 2<10:8>), select the oscillator source that is used at a Power-on Reset. The FRC Primary Oscillator with Postscaler (FRCDIV) is the default (unprogrammed) selection. The Secondary Oscillator, or one of the internal oscillators, may be chosen by programming these bit locations.

The Configuration bits allow users to choose between the various clock modes, as shown in Table 9-1.

9.2.1 CLOCK SWITCHING MODE CONFIGURATION BITS

The FCKSM<1:0> Configuration bits (Configuration Word 2<7:6>) are used to jointly configure device clock switching and the Fail-Safe Clock Monitor (FSCM). Clock switching is enabled only when FCKSM1 is programmed ('0'). The FSCM is enabled only when FCKSM<1:0> are both programmed ('00').

TABLE 9-1: CONFIGURATION BIT VALUES FOR CLOCK SELECTION

Oscillator Mode	Oscillator Source	POSCMD<1:0>	FNOSC<2:0>	Notes
Fast RC Oscillator with Postscaler (FRCDIV)	Internal	11	111	1, 2
(Reserved)	Internal	xx	110	1
Low-Power RC Oscillator (LPRC)	Internal	11	101	1
Secondary (Timer1) Oscillator (SOSC)	Secondary	11	100	1
Primary Oscillator (XT) with PLL Module (XTPLL)	Primary	01	011	
Primary Oscillator (EC) with PLL Module (ECPLL)	Primary	00	011	
Primary Oscillator (HS)	Primary	10	010	
Primary Oscillator (XT)	Primary	01	010	
Primary Oscillator (EC)	Primary	00	010	
Fast RC Oscillator with PLL Module (FRCPLL)	Internal	11	001	1
Fast RC Oscillator (FRC)	Internal	11	000	1

Note 1: OSCO pin function is determined by the OSCIOFCN Configuration bit.

2: This is the default oscillator mode for an unprogrammed (erased) device.

11.4.3.2 Output Mapping

In contrast to inputs, the outputs of the Peripheral Pin Select options are mapped on the basis of the pin. In this case, a control register associated with a particular pin dictates the peripheral output to be mapped. The RPORx registers are used to control output mapping. Each register contains two 6-bit fields, with each field being associated with one RPn pin (see Register 11-23 through Register 11-35). The value of the bit field corresponds to one of the peripherals and that peripheral's output is mapped to the pin (see Table 11-4).

Because of the mapping technique, the list of peripherals for output mapping also includes a null value of '000000'. This permits any given pin to remain disconnected from the output of any of the pin-selectable peripherals.

TABLE 11-4: SELECTABLE OUTPUT SOURCES (MAPS FUNCTION TO OUTPUT)

Output Function Number(1)	Function	Output Name
0	NULL(2)	Null
1	C1OUT	Comparator 1 Output
2	C2OUT	Comparator 2 Output
3	U1TX	UART1 Transmit
4	$\overline{\text{U1RTS}}$(3)	UART1 Request-to-Send
5	U2TX	UART2 Transmit
6	$\overline{\text{U2RTS}}$(3)	UART2 Request-to-Send
7	SDO1	SPI1 Data Output
8	SCK1OUT	SPI1 Clock Output
9	SS1OUT	SPI1 Slave Select Output
10	SDO2	SPI2 Data Output
11	SCK2OUT	SPI2 Clock Output
12	SS2OUT	SPI2 Slave Select Output
13	OC1	Output Compare 1
14	OC2	Output Compare 2
15	OC3	Output Compare 3
16	OC4	Output Compare 4
17	OC5	Output Compare 5
18	OC6	Output Compare 6
19	U3TX	UART3 Transmit
20	$\overline{\text{U3RTS}}$	UART3 Request-to-Send
21	U4TX	UART4 Transmit
22	$\overline{\text{U4RTS}}$(3)	UART4 Request-to-Send
23	SDO3	SPI3 Data Output
24	SCK3OUT	SPI3 Clock Output
25	SS3OUT	SPI3 Slave Select Output
26	C3OUT	Comparator 3 Output
27	MDOUT	DSM Modulator Output

Note 1: Setting the RPORx register with the listed value assigns that output function to the associated RPn pin.

2: The NULL function is assigned to all RPn outputs at device Reset and disables the RPn output function.

3: IrDA® BCLKx functionality uses this output.

REGISTER 11-14: RPINR20: PERIPHERAL PIN SELECT INPUT REGISTER 20

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SCK1R5	SCK1R4	SCK1R3	SCK1R2	SCK1R1	SCK1R0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SDI1R5	SDI1R4	SDI1R3	SDI1R2	SDI1R1	SDI1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **SCK1R<5:0>:** Assign SPI1 Clock Input (SCK1IN) to Corresponding RPn or RPIn Pin bits

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **SDI1R<5:0>:** Assign SPI1 Data Input (SDI1) to Corresponding RPn or RPIn Pin bits

REGISTER 11-15: RPINR21: PERIPHERAL PIN SELECT INPUT REGISTER 21

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	U3CTSR5	U3CTSR4	U3CTSR3	U3CTSR2	U3CTSR1	U3CTSR0
bit 15							bit 8

U-0	U-0	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
—	—	SS1R5	SS1R4	SS1R3	SS1R2	SS1R1	SS1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-14 **Unimplemented:** Read as '0'

bit 13-8 **U3CTSR<5:0>:** Assign UART3 Clear-to-Send ($\overline{\text{U3CTS}}$) to Corresponding RPn or RPIn Pin bits

bit 7-6 **Unimplemented:** Read as '0'

bit 5-0 **SS1R<5:0>:** Assign SPI1 Slave Select Input (SS1IN) to Corresponding RPn or RPIn Pin bits

REGISTER 15-2: OCxCON2: OUTPUT COMPARE x CONTROL REGISTER 2 (CONTINUED)

bit 4-0 **SYNCSEL<4:0>:** Trigger/Synchronization Source Selection bits

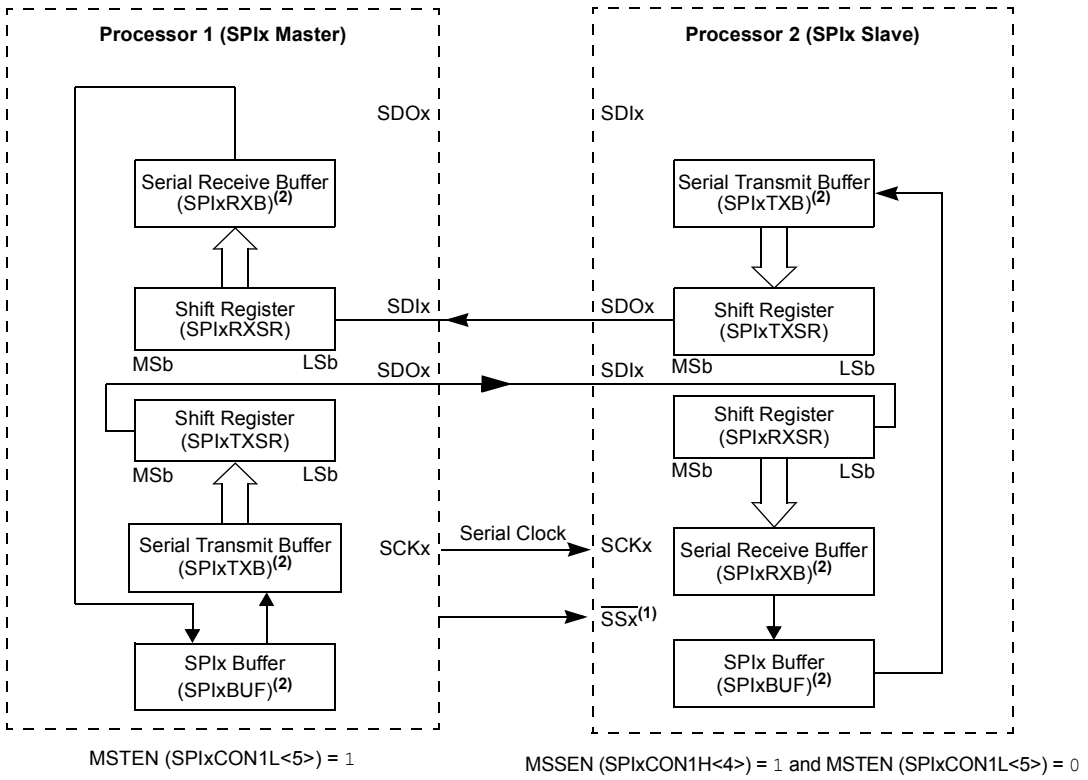
11111 = This OC module(1)
11110 = OCTRIG1 external input
11101 = OCTRIG2 external input
11100 = CTMU(2)
11011 = A/D(2)
11010 = Comparator 3(2)
11001 = Comparator 2(2)
11000 = Comparator 1(2)
10111 = Reserved
10110 = Reserved
10101 = Input Capture 6(2)
10100 = Input Capture 5(2)
10011 = Input Capture 4(2)
10010 = Input Capture 3(2)
10001 = Input Capture 2(2)
10000 = Input Capture 1(2)
01111 = Timer5
01110 = Timer4
01101 = Timer3
01100 = Timer2
01011 = Timer1
01010 = Reserved
01001 = Reserved
01000 = Reserved
00111 = Reserved
00110 = Output Compare 6(1)
00101 = Output Compare 5(1)
00100 = Output Compare 4(1)
00011 = Output Compare 3(1)
00010 = Output Compare 2(1)
00001 = Output Compare 1(1)
00000 = Not synchronized to any other module

Note 1: Never use an OCx module as its own trigger source, either by selecting this mode or another equivalent SYNCSELx setting.

2: Use these inputs as trigger sources only and never as sync sources.

3: The DCB<1:0> bits are double-buffered in PWM modes only (OCM<2:0> (OCxCON1<2:0>) = 111, 110).

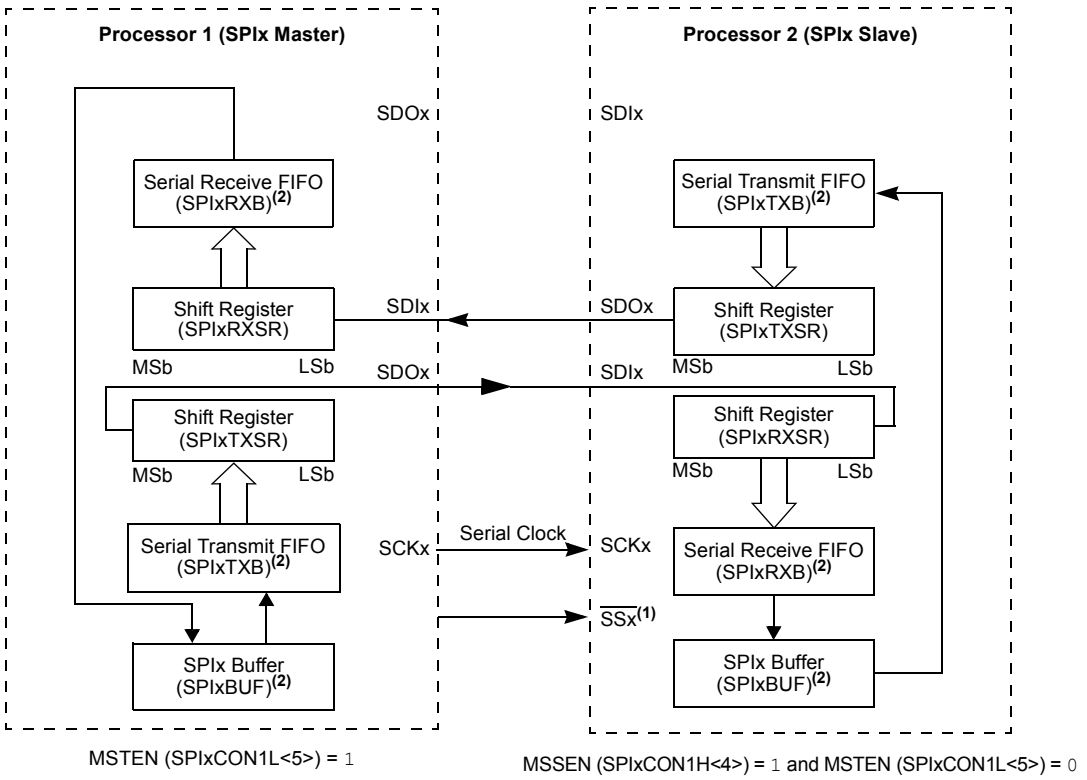
FIGURE 16-3: SPIx MASTER/SLAVE CONNECTION (STANDARD MODE)



Note 1: Using the $\overline{SSx}$ pin in Slave mode of operation is optional.

2: User must write transmit data to read the received data from SPIxBUF. The SPIxTXB and SPIxRXB registers are memory-mapped to SPIxBUF.

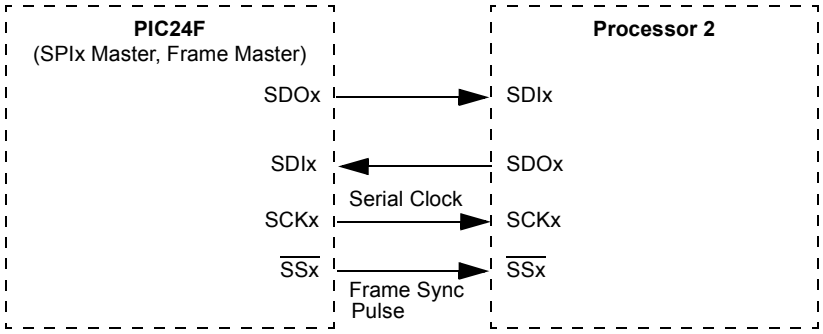
FIGURE 16-4: SPIx MASTER/SLAVE CONNECTION (ENHANCED BUFFER MODES)



Note 1: Using the $\overline{SSx}$ pin in Slave mode of operation is optional.

2: User must write transmit data to read the received data from SPIxBUF. The SPIxTXB and SPIxRXB registers are memory-mapped to SPIxBUF.

FIGURE 16-5: SPIx MASTER, FRAME MASTER CONNECTION DIAGRAM



REGISTER 18-3: UxTXREG: UARTx TRANSMIT REGISTER (NORMALLY WRITE-ONLY)

W-x	U-0	U-0	U-0	U-0	U-0	U-0	W-x
LAST(1)	—	—	—	—	—	—	UxTXREG8
bit 15							bit 8

W-x	W-x	W-x	W-x	W-x	W-x	W-x	W-x
UxTXREG7	UxTXREG6	UxTXREG5	UxTXREG4	UxTXREG3	UxTXREG2	UxTXREG1	UxTXREG0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15 **LAST:** Last Byte Indicator for Smart Card Support bits(1)

bit 14-9 **Unimplemented:** Read as '0'

bit 8 **UxTXREG8:** Data of the Transmitted Character bit (in 9-bit mode)

bit 7-0 **UxTXREG<7:0>:** Data of the Transmitted Character bits

Note 1: This bit is only available for UART1 and UART2.

REGISTER 18-4: UxADMD: UARTx ADDRESS MATCH DETECT REGISTER

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADMMASK7	ADMMASK6	ADMMASK5	ADMMASK4	ADMMASK3	ADMMASK2	ADMMASK1	ADMMASK0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
ADMADDR7	ADMADDR6	ADMADDR5	ADMADDR4	ADMADDR3	ADMADDR2	ADMADDR1	ADMADDR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **ADMMASK<7:0>:** UARTx ADMADDR<7:0> (UxADMD<7:0>) Masking bits

For ADMMASK<x>:

1 = ADMADDR<x> is used to detect the address match

0 = ADMADDR<x> is not used to detect the address match

bit 7-0 **ADMADDR<7:0>:** UARTx Address Detect Task Off-Load bits

Used with the ADMMASK<7:0> bits (UxADMD<15:8>) to off-load the task of detecting the address character from the processor during Address Detect mode.

REGISTER 22-4: CRYOTP: CRYPTOGRAPHIC OTP PAGE PROGRAM CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/HSC-x(1)	R/W-0(1)	R/S/HC-1	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/W-0(1)	R/S/HC-0(2)
PGMTST	OTPIE	CRYREAD(3,4)	KEYPG3	KEYPG2	KEYPG1	KEYPG0	CRYWR(3,4)
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
S = Settable bit	HC = Hardware Clearable bit	HSC = Hardware Settable/Clearable bit	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as '0'

bit 7 **PGMTST:** Key Storage/Configuration Program Test bit(1)

This bit mirrors the state of the TSTPGM bit and is used to test the programming of the secure OTP array after programming.

1 = TSTPGM (CFGPAGE<30>) is programmed ('1')
0 = TSTPGM is not programmed ('0')

bit 6 **OTPIE:** Key Storage/Configuration Program Interrupt Enable bit(1)

1 = Generates an interrupt when the current programming or read operation completes
0 = Does not generate an interrupt when the current programming or read operation completes; software must poll the CRYWR, CRYREAD or CRYBSY bit to determine when the current programming operation is complete

bit 5 **CRYREAD:** Cryptographic Key Storage/Configuration Read bit(3,4)

1 = This bit is set to start a read operation; read operation is in progress while this bit is set and CRYGO = 1
0 = Read operation has completed

bit 4-1 **KEYPG<3:0>:** Key Storage/Configuration Program Page Select bits(1)

1111
•
• = Reserved
•
1001
1000 = OTP Page 8
0111 = OTP Page 7
0110 = OTP Page 6
0101 = OTP Page 5
0100 = OTP Page 4
0011 = OTP Page 3
0010 = OTP Page 2
0001 = OTP Page 1
0000 = Configuration Page (CFGPAGE, OTP Page 0)

bit 0 **CRYWR:** Cryptographic Key Storage/Configuration Program bit(2,3,4)

1 = Programs the Key Storage/Configuration bits with the value found in CRYTXTC<63:0>
0 = Program operation has completed

Note 1: These bits are reset on systems Resets or whenever the CRYMD bit is set.

2: These bits are reset on systems Resets, when the CRYMD bit is set or when CRYGO is cleared.

3: Set this bit only when CRYON = 1 and CRYGO = 0. Do not set CRYREAD or CRYWR both, at any given time.

4: Do not clear CRYON or these bits while they are set; always allow the hardware operation to complete and clear the bit automatically.

TABLE 22-2: AES KEY MODE/SOURCE SELECTION

Mode of Operation	KEYMOD<1:0>	KEYSRC<3:0>	Key Source		OTP Address
			SKEYEN = 0	SKEYEN = 1	
128-Bit AES	00	0000[1]	CRYKEY<127:0>		—
		0001	AES Key #1	Key Config Error[2]	<127:0>
		0010	AES Key #2		<255:128>
		0011	AES Key #3		<383:256>
		0100	AES Key #4		<511:384>
		1111	Reserved[2]		—
		All Others	Key Config Error[2]		—
192-Bit AES	01	0000[1]	CRYKEY<191:0>		—
		0001	AES Key #1	Key Config Error[2]	<191:0>
		0010	AES Key #2		<383:192>
		1111	Reserved[2]		—
		All Others	Key Config Error[2]		—
256-Bit AES	10	0000[1]	CRYKEY<255:0>		—
		0001	AES Key #1	Key Config Error[2]	<255:0>
		0010	AES Key #2		<511:256>
		1111	Reserved[2]		—
		All Others	Key Config Error[2]		—
(Reserved)	11	xxxx	Key Config Error[2]		—

Note 1: This configuration is considered a Key Configuration Error (KEYFAIL bit is set) if SWKYDIS is also set.

2: The KEYFAIL bit (CRYSTAT<1>) is set when these configurations are selected and remains set until a valid configuration is selected.

REGISTER 26-1: CVRCON: COMPARATOR VOLTAGE REFERENCE CONTROL REGISTER

U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0
—	—	—	—	—	CVREFP	CVREFM1	CVREFM0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
CVREN	CVROE	CVRSS	CVR4	CVR3	CVR2	CVR1	CVR0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as '0'

bit 10 **CVREFP:** Comparator Voltage Reference Select bit (valid only when CREF is '1')
1 = VREF+ is used as a reference voltage to the comparators
0 = The CVR (4-bit DAC) within this module provides the reference voltage to the comparators

bit 9-8 **CVREFM<1:0>:** Comparator Voltage Band Gap Reference Source Select bits
(valid only when CCH<1:0> = 11)
00 = Band gap voltage is provided as an input to the comparators
01 = Band gap voltage, divided by two, is provided as an input to the comparators
10 = Reserved
11 = VREF+ pin is provided as an input to the comparators

bit 7 **CVREN:** Comparator Voltage Reference Enable bit
1 = CVREF circuit is powered on
0 = CVREF circuit is powered down

bit 6 **CVROE:** Comparator VREF Output Enable bit
1 = CVREF voltage level is output on the CVREF pin
0 = CVREF voltage level is disconnected from the CVREF pin

bit 5 **CVRSS:** Comparator VREF Source Selection bit
1 = Comparator reference source, CVRSRC = VREF+ – VREF-
0 = Comparator reference source, CVRSRC = AVDD – AVSS

bit 4-0 **CVR<4:0>:** Comparator VREF Value Selection bits
CVREF = (CVR<4:0>/32) • (CVRSRC)

30.2 MPLAB XC Compilers

The MPLAB XC Compilers are complete ANSI C compilers for all of Microchip's 8, 16 and 32-bit MCU and DSC devices. These compilers provide powerful integration capabilities, superior code optimization and ease of use. MPLAB XC Compilers run on Windows, Linux or MAC OS X.

For easy source level debugging, the compilers provide debug information that is optimized to the MPLAB X IDE.

The free MPLAB XC Compiler editions support all devices and commands, with no time or memory restrictions, and offer sufficient code optimization for most applications.

MPLAB XC Compilers include an assembler, linker and utilities. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. MPLAB XC Compiler uses the assembler to produce its object file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

30.3 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code, and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB X IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multipurpose source files
- Directives that allow complete control over the assembly process

30.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

30.5 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC DSC devices. MPLAB XC Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command-line interface
- Rich directive set
- Flexible macro language
- MPLAB X IDE compatibility

TABLE 32-3: DC CHARACTERISTICS: TEMPERATURE AND VOLTAGE SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
Operating Voltage							
DC10	VDD	**Supply Voltage**	2.0	—	3.6	V	BOR disabled
			VBOR	—	3.6	V	BOR enabled
DC12	VDR	**RAM Data Retention Voltage**(1)	Greater of: VPORREL or VBOR	—	—	V	VBOR used only if BOR is enabled (BOREN = 1)
DC16	VPOR	**VDD Start Voltage** to Ensure Internal Power-on Reset Signal	VSS	—	—	V	**(Note 2)**
DC16A	VPORREL	**VDD Power-on Reset Release Voltage**	1.80	1.88	1.95	V	**(Note 3)**
DC17A	SRVDD	**Recommended VDD Rise Rate** to Ensure Internal Power-on Reset Signal	0.05	—	—	V/ms	0-3.3V in 66 ms, 0-2.5V in 50 ms **(Note 2)**
DC17B	VBOR	**Brown-out Reset Voltage** on VDD Transition, High-to-Low	2.0	2.1	2.2	V	**(Note 3)**

Note 1: This is the limit to which VDD may be lowered and the RAM contents will always be retained.

2: If the VPOR or SRVDD parameters are not met, or the application experiences slow power-down VDD ramp rates, it is recommended to enable and use BOR.

3: On a rising VDD power-up sequence, application firmware execution begins at the higher of the VPORREL or VBOR level (when BOREN = 1).

TABLE 32-11: INTERNAL VOLTAGE REGULATOR SPECIFICATIONS

Operating Conditions: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended							
Param No.	**Symbol**	**Characteristics**	**Min**	**Typ**	**Max**	**Units**	**Comments**
DVR	TVREG	Voltage Regulator Start-up Time	—	10	—	μs	VREGS = 1 with any POR or BOR
DVR10	VBG	Internal Band Gap Reference	—	1.2	—	V	
DVR11	TBG	Band Gap Reference Start-up Time	—	1	—	ms	
DVR20	VRGOUT	Regulator Output Voltage	—	1.8	—	V	VDD > 1.9V
DVR21	CEFC	External Filter Capacitor Value	4.7	10	—	μF	Series resistance < 3Ω recommended; < 5Ω required
DVR30	VLVR	Low-Voltage Regulator Output Voltage	—	1.2	—	V	RETEN = 1, $\overline{\text{LPCFG}}$ = 0

TABLE 32-12: HIGH/LOW-VOLTAGE DETECT CHARACTERISTICS

Operating Conditions: -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended								
Param No.	**Symbol**	**Characteristic**		**Min**	**Typ**	**Max**	**Units**	**Conditions**
DC18	VHLVD	HLVD Voltage on VDD Transition	HLVDL<3:0> = 0100(1)	3.45	3.59	3.74	V	
			HLVDL<3:0> = 0101	3.33	3.45	3.58	V	
			HLVDL<3:0> = 0110	3.0	3.125	3.25	V	
			HLVDL<3:0> = 0111	2.8	2.92	3.04	V	
			HLVDL<3:0> = 1000	2.7	2.81	2.93	V	
			HLVDL<3:0> = 1001	2.50	2.6	2.70	V	
			HLVDL<3:0> = 1010	2.4	2.52	2.64	V	
			HLVDL<3:0> = 1011	2.30	2.4	2.50	V	
			HLVDL<3:0> = 1100	2.20	2.29	2.39	V	
			HLVDL<3:0> = 1101	2.1	2.19	2.28	V	
			HLVDL<3:0> = 1110	2.0	2.08	2.17	V	
DC101	VTHL	HLVD Voltage on HLVDIN Pin Transition	HLVDL<3:0> = 1111	—	1.2	—	V	

Note 1: Trip points for values of HLVD<3:0> from '0000' to '0011' are not implemented.

FIGURE 32-12: OCx/PWM MODULE TIMING CHARACTERISTICS

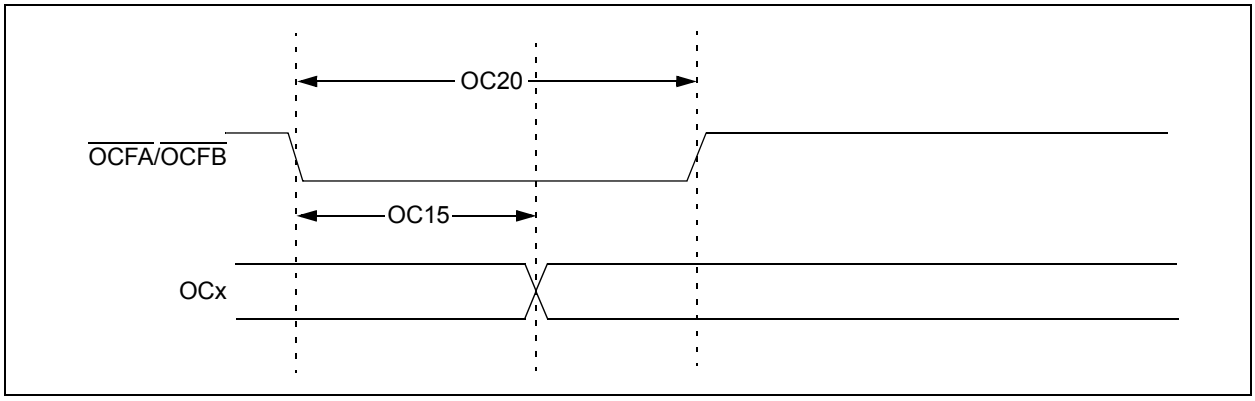
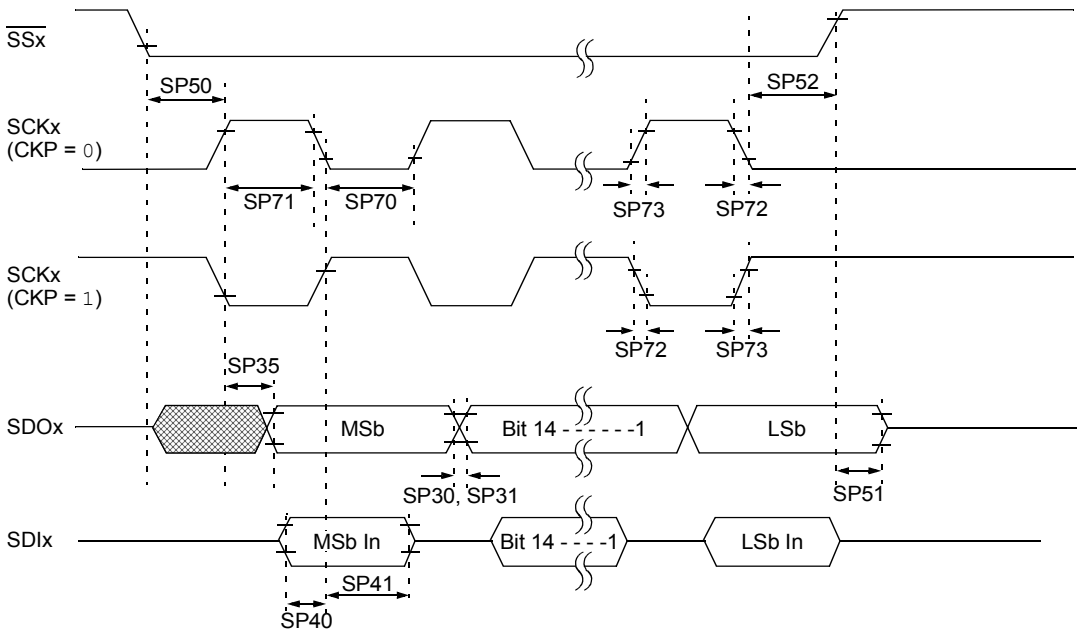


TABLE 32-34: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	

Note 1: These parameters are characterized but not tested in manufacturing.

FIGURE 32-15: SPIx MODULE SLAVE MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 32-2 for load conditions.

TABLE 32-37: SPIx MODULE SLAVE MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic(1)**	**Min**	**Typ(2)**	**Max**	**Units**	**Conditions**
SP70	TscL	SCKx Input Low Time	30	—	—	ns	
SP71	TscH	SCKx Input High Time	30	—	—	ns	
SP72	TscF	SCKx Input Fall Time(3)	—	10	25	ns	
SP73	TscR	SCKx Input Rise Time(3)	—	10	25	ns	
SP30	TdoF	SDOx Data Output Fall Time(3)	—	—	—	ns	See Parameter DO32
SP31	TdoR	SDOx Data Output Rise Time(3)	—	—	—	ns	See Parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid After SCKx Edge	—	—	30	ns	
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	20	—	—	ns	
SP50	TssL2scH, TssL2scL	$\overline{SSx}$ ↓ to SCKx ↑ or SCKx Input	120	—	—	ns	
SP51	TssH2doZ	$\overline{SSx}$ ↑ to SDOx Output High-Impedance(3)	10	—	50	ns	
SP52	TscH2ssH, TscL2ssH	$\overline{SSx}$ After SCKx Edge	1.5 TCY + 40	—	—	ns	

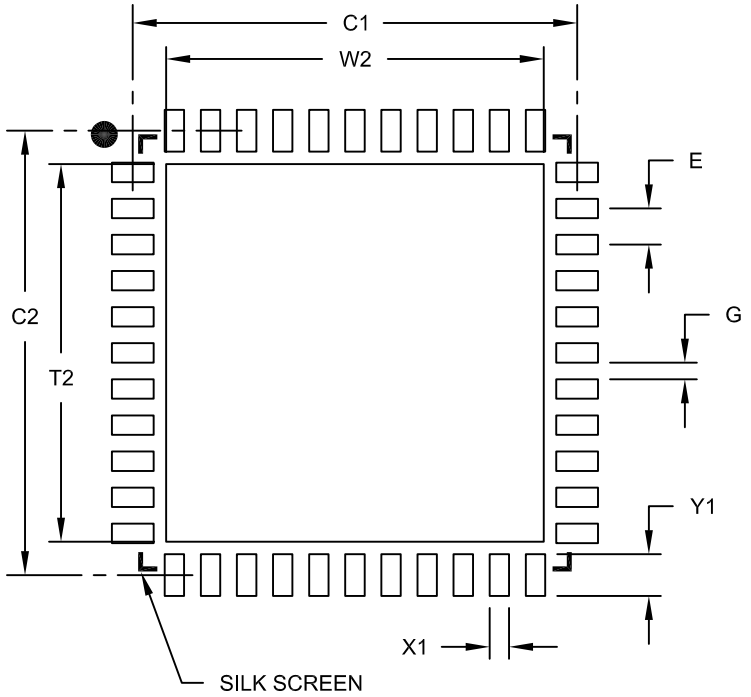
Note 1: These parameters are characterized but not tested in manufacturing.

2: Data in "Typ" column is at 3.3V, +25°C unless otherwise stated.

3: Assumes 50 pF load on all SPIx pins.

44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.65 BSC	
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
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ISBN: 978-1-63277-205-3

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